

PCBRM15/System 5.2



Lead-Free Selective Soldering & Rework
of Through-Hole Components &
Thermally Challenging Assemblies

The PCBRM System 5.2 adds
a 6500 watt Preheater



**Precision Operation Control, Minimal Copper Dissolution and Board Delamination,
Fast and Uniform Heating for Effective Lead-Free Selective Soldering**

Advantages

- Lead-Free & thermally challenging assemblies.
- Minimal Copper dissolution in PCB barrels.
- Minimal board delamination.
- Fast and uniform heating.
- Precise operating controls and alignment system.
- Quick component removal and soldering.
- Reliability, simple design, trouble-free operation.

Precise Operating Control

- Solder Wave Contact - Cycle duration automatically sets time solder contacts board.
- Solder Wave Flow Rate - allows level wave for any flow well shape or size. Three (3) stage settings for enhanced process control.
- Temperature - Closed-loop control of set temperature. System can be set to 615°F (325°C).

Pumping System & Solder Pot

- Cast iron solder pot and titanium/cast iron impeller pump are designed to withstand aggressive, lead-free solder.
- Minimal dross accumulation and level solder wave.

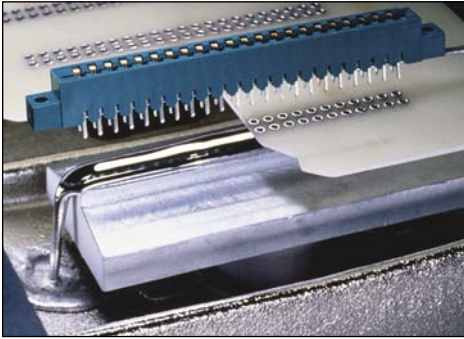
Alignment System

- X, Y, Z Board Carrier - Cantilever rails, linear bearings and rigid cast framework provides large board holding, precision rail movement and continuous usage.
- PCB Hole Cleaning System (option) - Component is aligned over solder wave then cleaning hood is positioned to clean PCB barrels.

Titanium Flow Wells

- Solder flow is directed away from adjacent components.
- High pin count leads are heated simultaneously for a quick process.
- Locating pins position the lead pattern over the wave.
- External heaters maintain uniform heat on large wells.
- Fixtures for multiple and irregularly shaped boards.

Precision Control For Lead-Free & Thermally Challenging Assemblies



SOLDER FLOW MATCHES LEAD PATTERN



TITANIUM FLOW WELLS



CUSTOM WELLS & MATCHING CLEANING HOODS



REGULAR, MULTIPLE & IRREGULARLY SHAPED BOARDS



ROBUST SOLDER POT & PUMP

Technical Data

PCBRM15

- Physical Dimensions: 32"W x 32"D x 26"H
- Solder Capacity: 35 lbs. Weight with Solder: 125 lbs.
- Compressed Air: 40-80 psi, clean moisture free
- Electrical: 208/220V, 15 amps @ 220V, 50/60Hz single phase, 2500 watts.

PCBRM System 5.2

- Physical Dimensions: 76"W x 33"D x 28"H
- Board Carrier Size: 24"W x 20"D
- Solder Capacity: 35 lbs. Weight with Solder: 230 lbs.
- Compressed Air: 40-80 psi, clean moisture free
- Electrical: 45 amps @ 220V, 50/60Hz, 10000 watts.

TECHNICAL DATA SUBJECT TO CHANGE.

**PCBRM System 5.2 adds
a Preheater (6500 watt)**



Options

- **Flow Well Heater Control Module** (ST350)
- **Air Cleaning System** (APS)
- **Fume Extraction Manifold** (3005.02.040)

Recommended Spare Parts

- **Drive Belt (high temp)** (12467)
- **Pump Bearing (set of 2)** (9001.09.020)
- **Thermocouple & Fitting (process)** (12801)
- **Thermocouple & Fitting (overtemp)** (12802)